

### 1. Features and Benefits

- End-of-line programmable sensor
- Ratiometric analog output
- Flexible Supply Voltage with factory selectable 5V or 3.3V mode
- Measurement range from  $\pm 12.5$  to  $\pm 400$ mT
- High speed sensing
  - DC to 400kHz bandwidth
  - 2 $\mu$ s response time
- High linearity down to  $\pm 0.5\%$  full scale
- Low noise
- AEC-Q100 – Grade 0 Automotive Qualification
- Very low thermal drift for wide temperature range
  - Offset drift (<5mV)
  - Sensitivity drift (<1%)
- Internal overcurrent detection
- RoHS compliant
- Available in SIP4-VA (MSL-1) and SOIC8 packages (MSL-3)



### 2. Application Examples

- High Voltage Traction Motor Inverter
- 48V Boost Recuperation Inverter
- DCDC Converter
- Smart Battery Junction Boxes
- Smart Fuse Overcurrent Detection
- Redundant monitoring of Battery Management System (BMS)

### 3. Description

The MLX91219 is a monolithic Hall-effect sensor which is sensitive to the flux density applied orthogonally to the IC surface. The sensor provides an analog output voltage proportional to the applied magnetic flux density.

The transfer characteristic of the MLX91219 is factory trimmed over temperature, and is programmable (offset, sensitivity, filtering, internal overcurrent threshold) during end-of-line customer calibration. With the 400kHz bandwidth and fast response time, it is particularly adapted for high speed applications such as inverters and converters where fast response time due to fast switching is required.

In a typical current sensing application, the sensor is used in combination with a ring shaped soft ferromagnetic core. This core is recommended to be laminated for high bandwidth applications. The MLX91219 is placed in a small air gap and the current conductor – a bus bar or a cable – is passed through the inner part of the ferromagnetic ring. On the one hand the ring concentrates and amplifies the magnetic flux seen by the sensor IC, and at the same time it attenuates external magnetic field disturbances.

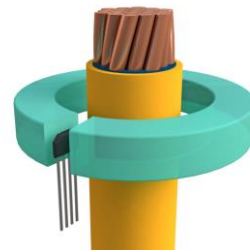


Figure 1. Typical Current Sensing Application

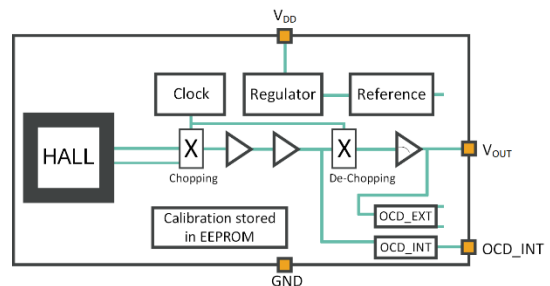


Figure 2. General Block Diagram

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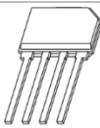
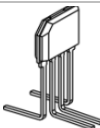
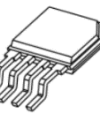
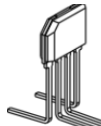
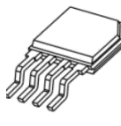
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## 4. Ordering Information

Product Code	Temperature	Package	Option Code	Packing Form	Typical Sensitivity	Supply Voltage	OCD Level
MLX91219	L	VA	AAA-500	CR	7 mV/mT	5V	136 %FS
MLX91219	L	VA	AAA-501	RE	10mV/mT	5V	136 %FS
MLX91219	L	DC	ARA-501	RE	10mV/mT	5V	142 %FS
MLX91219	L	VA	AAA-502	CR	15mV/mT	5V	136 %FS
MLX91219	L	VA	AAA-503	CR	25mV/mT	5V	136 %FS
MLX91219	L	VA	AAT-505	RE	10mV/mT	5V	90 %FS

*Table 1: Available ordering codes.*

**Legend:**

Temperature Code	<b>L</b>	from -40°C to 150°C ambient temperature		
Package Code	<b>VA</b>	“VA” for SIP-4 VA package		
	<b>DC</b>	“DC” for SOIC8 package		
Option Code	<b>Axx-xxx</b>	“A” for Silicon revision		
	<b>xAx-xxx</b>	“A” for ratiometric output (only for SIP-4 VA package)		
	<b>xRx-xxx</b>	“R” for fixed output (only for SOIC8 package)		
	<b>xFx-xxx</b>	“F” for fixed output (only for SOIC8 package)		
	<b>xxA-xxx</b>	Default straight leads	<b>xxA-xxx</b>	
	<b>xxR-xxx</b>	TF-VA-2L-1.27-5.34-91.3-4.3	<b>xxR-xxx</b>	
	<b>xxS-xxx</b>	TF-VA-2L-1.27-3.7-91.3-4.3	<b>xxS-xxx</b>	
	<b>xxT-xxx</b>	TF-VA-2L-1.27-1.68-91.8-3	<b>xxT-xxx</b>	
	<b>xxZ-xxx</b>	TF-VA-ZB-1.27-2.15	<b>xxZ-xxx</b>	
	<b>xxx-3xx</b>	“3” for 3.3 V supply, bipolar output		
<b>xxx-5xx</b>	“5” for 5 V supply, bipolar output			
<b>xxx-x00</b>	Typical sensitivity of 7 mV/mT and overcurrent detection of 128 %full scale			
<b>xxx-x01</b>	Typical sensitivity of 10 mV/mT and overcurrent detection of 128 %full scale			
<b>..</b>	..			
Packing Form	<b>CR</b>	Carton Reel – Radial taping		
	<b>RE</b>	Plastic Tape on Reel		
	<b>SP</b>	Sample pack		
Ordering Example	<b>“MLX91219LVA-AAA-500-CR”</b> MLX91219 Conventional Hall current sensor in SIP4-VA package, temperature range -40°C to 150°C. Sensitivity 7 mV/mT. 5V Supply, bipolar ratiometric output. Parts delivered in Carton Reel.			

*Table 2: Legend ordering codes.*

Melexis is continuously expanding its product portfolio by adding new option codes to better meet the needs of our customer’s applications. This table is being updated frequently, please go to the Melexis website to download the latest version of this datasheet. For custom transfer characteristics, please contact your local Melexis Sales representative or distributor.

## 5. Functional Diagram

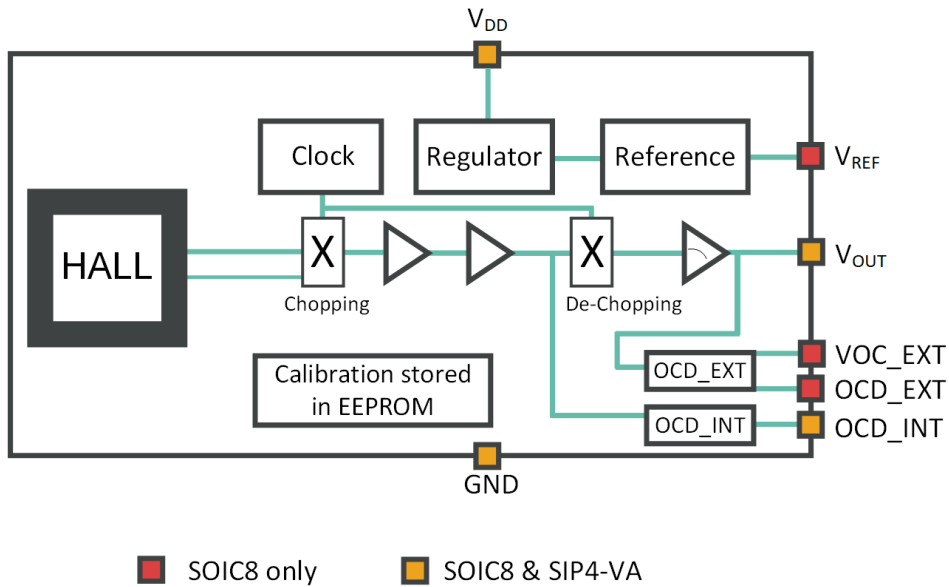


Figure 3: Block Diagram of the MLX91219.

## Ratiometric Mode

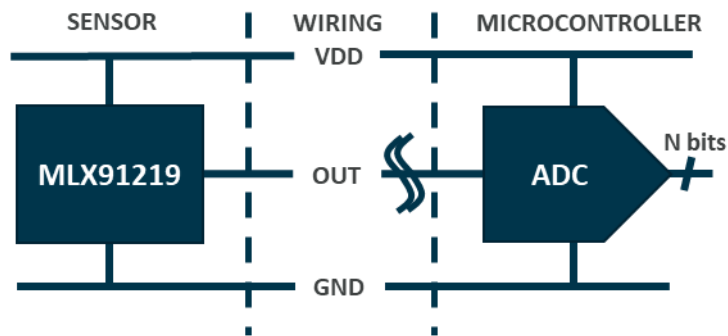


Figure 4: Schematic of ratiometric mode

No matter if the  $V_{DD}$  line is at 5V or deviating  $\pm 10\%$ , the ADC code for a given measured current will always be the same as the ADC is supplied by the same voltage as the sensor. The sensor has a sensitivity expressed in  $\%V_{DD}/A$ .

## Differential or Fixed Mode<sup>(1)</sup>

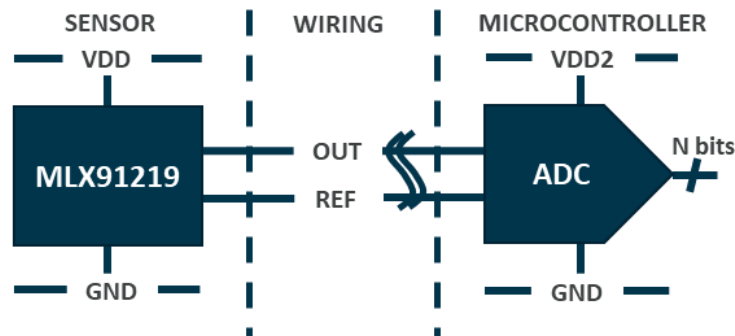


Figure 5: Schematic of fixed mode

In this particular case the ADC does not necessarily share the same supply voltage with the sensor. For this reason, the sensor is calibrated with an absolute sensitivity regardless of the actual supply voltage. The output signal can be reconstructed by taking the difference between the output and the reference voltage from the IC. The ADC gets these two signals as inputs for establishing the sensed current accurately, and is not influenced by the supply voltage differences between both sensor and microcontroller, if applicable. Only available in SOIC8 package.

Parameter	Ratiometric Mode	Differential or Fixed Mode
<b>Output Signal</b>	$V_{OUT} [\%V_{DD}]$  Example: output is 2.5V when supply is 5V → output is then 50% $V_{DD}$ . If the supply ( $V_{DD}$ ) increases with 5% to 5.25V the sensor output will (for the same measured input current) scale <b>proportionally</b> with the supply voltage, becoming 2.625V, but as a percentage (i.e. ratiometrically seen) it remains at 50% of $V_{DD}$ .	$V_{OUT} - V_{REF} [V]$  Example: output is 2.501V and $V_{REF}$ is 2.501V when supply is 5V. When the supply voltage is increasing to 5.1V due to supply system variation, the sensor will still maintain the same “fixed” output values $V_{OUT}$ and $V_{REF}$ .
<b>Offset</b>	$V_{OUT}[0A] = 50 [\%V_{DD}]$ (factory trimmed)	$V_{REF} = 2.5 [V]$ (factory trimmed) $V_{OUT}[0A] - V_{REF} = 0 [V]$
<b>Offset ratiometric</b>	Yes	No
<b>Sensitivity</b>	$[\%V_{DD}/A]$	$[mV/A]$
<b>Sensitivity ratiometric</b>	Yes	No
<b>Measured Current</b>	$(V_{OUT} - V_{OUT}[0A]) / \text{Sensitivity}$	$(V_{OUT} - V_{REF}) / \text{Sensitivity}$

Table 3: Parameters of differential and fixed modes

(1) Only available in SOIC8 package. More information can be found in Application Note ANCurrent\_sensors\_gen2\_ReferencePin on [www.melexis.com](http://www.melexis.com)

## 6. Glossary of Terms

Terms	Definition
TC	Temperature Coefficient
FS	Full Scale, output referred. Corresponds to 2V excursion around 2.5V at 5V supply or 1.25V excursion from 1.65V at 3.3V supply for bipolar designs
T, mT	Tesla, milliTesla = units for the magnetic flux density
G	Gauss = unit for the magnetic flux density [1mT = 10G]
OCD	Overcurrent Detection
MSL	Moisture Sensitivity Level

Table 4: Glossary of Terms

## 7. Pin Definitions and Descriptions

Note: MLX91219 is not pin-to-pin compatible with MLX91209 or MLX91217.

### 7.1. SIP-4 VA Package

Pin #	Name	Type	Description
1	VDD	Supply	Supply voltage
2	OUT	Analog Output	Output voltage (measurement)
3	OCD_INT	Analog Output	Overcurrent detection based on internal threshold
4	GND	Supply	Ground voltage

Table 5: Pin definitions and descriptions.

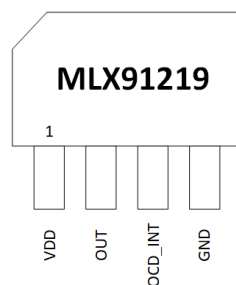


Figure 6: Pinout of SIP4-VA package.



## 7.2. SOIC8 package

Pin #	Name	Type	Description
1	VREF	Analog	Reference voltage
2	OUT	Analog Output	Output voltage (measurement)
3	GND	Supply	Ground voltage
4	VDD	Supply	Supply voltage
5	NC	-	Not connected
6	OCD_EXT	Analog Output	Overcurrent detection based on external threshold
7	OCD_INT	Analog Output	Overcurrent detection based on internal threshold
8	VOC_EXT	Analog Input	External threshold for the OCD

Table 6: Pin definitions and descriptions.

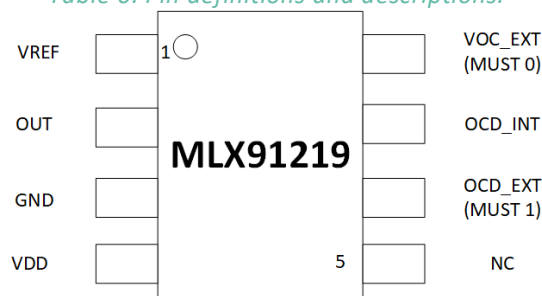


Figure 7: Pinout of SOIC8 package.

## 8. Absolute Maximum Ratings

Exceeding the absolute maximum ratings may cause permanent damage. Exposure to absolute maximum-rated conditions for extended periods of time may affect device reliability.

Parameter	Symbol	Value	Unit
Positive Supply Voltage (overvoltage)	$V_{DD}$	+8	V
Positive Pin Voltage <sup>1</sup>	$V_{PIN}$	$V_{DD} + 0.3$	V
Output Short Circuit Current to GND	$I_{SHORT\_GND}$	-100	mA
Output Short Circuit Current to $V_{DD}$	$I_{SHORT\_VDD}$	60	mA
Reverse Pin Voltage <sup>1</sup>	$V_{min\_REV}$	$GND - 0.3$	V
Output Sinking Current	$I_{out\_max}$	50	mA
Maximum Junction Temperature	$T_{J\_MAX}$	165	°C
Operating Ambient Temperature Range	$T_A$	-40 to +150	°C
Storage Temperature Range	$T_S$	-55 to +165	°C
Human Body ESD Protection	$ESD_{HBM}$	2	kV
Charged Device Model ESD Protection	$ESD_{CDM}$	500	V

Table 7: Absolute maximum ratings.

<sup>1</sup> Except  $V_{DD}$  and GND

## 9. General Electrical Specifications

Operating Parameters  $T_A = -40$  to  $150^\circ\text{C}$ ,  $V_{DD}=5$  V or 3.3 V factory trimmed devices unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Nominal Supply Voltage	$V_{DD}$	MLX91219Lxx-Axx-5xx MLX91219Lxx-Axx-3xx	4.5 3.135	5 3.3	5.5 3.465	V
Positive Supply Voltage (maintaining application mode)	$V_{DD}$			6.5		V
Supply Current	$I_{DD}$	Without $R_{LOAD}$ on output, in application mode $V_{DD} = 5$ V $V_{DD} = 3.3$ V		15.5 15	19 18	mA
$V_{OUT}$ Output Resistance	$R_{OUT}$	$V_{OUT} = 50\%V_{DD}$ , $I_{LOAD} = 10$ mA		1	5	$\Omega$
Output Capacitive Load	$C_{LOAD}$	Output amplifier stability is optimized for this typical value	0	4.7	6	nF
Output Leakage current	$I_{LEAK}$	High impedance mode, $T_A=150^\circ\text{C}$		6	20	$\mu\text{A}$
Output Voltage Linear Swing	$V_{OUT\_LSW}$	$V_{DD} > 4.6$ V for Fixed Mode versions	10		90	$\%V_{DD}$

Table 8: General electrical parameters.

## 10. Magnetic specification

Operating Parameters  $T_A = -40$  to  $150^\circ\text{C}$ ,  $V_{DD}=5$  V or 3.3 V factory trimmed unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Operational Magnetic Field Range	$B_{OP}$				$\pm 400$	mT
Linearity Error (Magnetic)	NL	B within $B_{OP}$ , $T_A = 25^\circ\text{C}$			$\pm 0.5$	%FS
Programmable Sensitivity	$S_{PROG}$	Generic part	5		105	mV/mT
		MLX91219LVA-AAA-500	6.5	7	22.5	
		MLX91219LVA-AAA-501	6.5	10	22.5	
		MLX91219LDC-ARA-501	6.5	10	22.5	
		MLX91219LVA-AAA-502	6.5	15	22.5	
		MLX91219LVA-AAA-503	16	25	55	
MLX91219LVA-AAT-505	6.5	10	22.5			
Sensitivity Programming Resolution	$S_{RES}$	$B = B_{OP}$		0.5		%

Table 9: Magnetic specification.

## Analog output specification

### 10.1. SIP-4 VA Accuracy specifications

Operating Parameters  $T_A = -40$  to  $150^\circ\text{C}$ ,  $V_{DD}=5$  V or 3.3 V factory trimmed unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Voltage Output Quiescent	$V_{OQ}$	No magnetic field applied, $T_A=25^\circ\text{C}$	-5		5	mV
Ratiometric Offset Error <sup>2</sup>	$\Delta R_{VOQ}$	$V_{DD} = 5V$ $V_{DD} = 3.3V$		1.6 1		mV/% $V_{DD}$
Thermal Offset Drift <sup>3</sup>	$\Delta^T V_{OQ}$	$T_A = -40$ to $125^\circ\text{C}$ $T_A = -40$ to $150^\circ\text{C}^4$	-5	$\pm 5$	5	mV
Total Offset drift <sup>5</sup>	$\Delta V_{OQ}$			$\pm 6$		mV
Ratiometric Sensitivity Error <sup>2</sup>	$\Delta^R S$			0.16		%/% $V_{DD}$
Thermal Sensitivity Drift <sup>3</sup>	$\Delta^T S$	$T_A = -40^\circ\text{C}$ to $125^\circ\text{C}$ $T_A = -40^\circ\text{C}$ to $150^\circ\text{C}^4$	-1	$\pm 1$	1	%S
Total Sensitivity Drift <sup>5</sup>	$\Delta S$			$\pm 1.5$		%S
Input referred noise spectral density	$N_{SD}$	within BW = 1 .. 400kHz, Max Gain		210		nT/VHz

Table 10: Accuracy specifications – analog parameters.

The accuracy specifications are defined for the factory calibrated sensitivity. The achievable accuracy is dependent on the user's end-of-line calibration. Resolution for offset and offset drift calibration is better than 0.05% $V_{DD}$ . Trimming capability is higher than measurement accuracy. End-user calibration can therefore increase the accuracy of the system.

<sup>2</sup> Ratiometry Error is verified at maximum  $V_{DD}$  deviation (5% $V_{DD}$  at 3.3V and 10% $V_{DD}$  at 5V) over temperature in production. Typical values are the maximum mean  $\pm 3$  sigma out of all characterized lots.

<sup>3</sup> Performance after factory trimming.

<sup>4</sup> Based on results from AEC-Q003 Characterization. Typical values are the maximum mean  $\pm 3$  sigma out of all characterized lots.

<sup>5</sup> After 1000h HTOL at  $T_A = 155^\circ\text{C}$  with respect to after pre-conditioning at  $T_A = 35^\circ\text{C}$ . Pre-conditioning is performed with MSL level 3 based on J-STD-020. Typical values are the highest average  $\pm 3$  sigma across all qualification lots.

## 10.2. SOIC8 Accuracy specifications

Operating Parameters  $T_A = -40$  to  $150^\circ\text{C}$ ,  $V_{DD} = 5\text{ V}$  or  $3.3\text{ V}$  factory trimmed unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Voltage Reference	$V_{REF}$	$T_A = 25^\circ\text{C}$ , xFx-5xx (fixed) versions $T_A = 25^\circ\text{C}$ , xFx-3xx (fixed) versions		2.5 1.65		V
Thermal Reference Drift	$\Delta T_{VREF}$	Variation versus $25^\circ\text{C}$ , for fixed output			$\pm 150$	ppm/ $^\circ\text{C}$
Non-ratiometric VREF Error	$\Delta V_{REF}$	Fixed mode devices (only SOIC8)	-3		3	mV
Voltage Output Quiescent	$V_{OQ}$	No magnetic field applied, $T_A = 25^\circ\text{C}$	-5		5	mV
Ratiometric Offset Error <sup>6</sup>	$\Delta R_{VOQ}$	$V_{DD} = 5\text{V}$ $V_{DD} = 3.3\text{V}$		1.6 1		mV/ $\%V_{DD}$
Thermal Offset Drift <sup>7</sup>	$\Delta^T V_{OQ}$	$T_A = -40$ to $125^\circ\text{C}$ $T_A = -40$ to $150^\circ\text{C}$ <sup>8</sup>	-5	$\pm 6$	5	mV
Total Offset drift <sup>9</sup>	$\Delta V_{OQ}$			$\pm 6$		mV
Ratiometric Sensitivity Error <sup>2</sup>	$\Delta^R S$			0.16		$\%/\%V_{DD}$
Thermal Sensitivity Drift <sup>3</sup>	$\Delta^T S$	$T_A = -40^\circ\text{C}$ to $125^\circ\text{C}$ $T_A = -40^\circ\text{C}$ to $150^\circ\text{C}$ <sup>4</sup>	-1	$\pm 1.3$	1	$\%S$
Total Sensitivity Drift <sup>5</sup>	$\Delta S$			$\pm 1.5$		$\%S$
Input referred noise spectral density	$N_{SD}$	within BW = 1 .. 400kHz, Max Gain		210		nT/ $\sqrt{\text{Hz}}$

Table 11: Accuracy specifications – analog parameters.

The accuracy specifications are defined for the factory calibrated sensitivity. The achievable accuracy is dependent on the user's end-of-line calibration. Resolution for offset and offset drift calibration is better than  $0.05\%V_{DD}$ . Trimming capability is higher than measurement accuracy. End-user calibration can therefore increase the accuracy of the system.

<sup>6</sup> Ratiometry Error is verified at maximum  $V_{DD}$  deviation ( $5\%V_{DD}$  at  $3.3\text{V}$  and  $10\%V_{DD}$  at  $5\text{V}$ ) over temperature in production. Typical values are the maximum mean  $\pm 3$  sigma out of all characterized lots.

<sup>7</sup> Performance after factory trimming.

<sup>8</sup> Based on results from AEC-Q003 Characterization. Typical values are the maximum mean  $\pm 3$  sigma out of all characterized lots.

<sup>9</sup> After 1000h HTOL at  $T_A = 155^\circ\text{C}$  with respect to after pre-conditioning at  $T_A = 35^\circ\text{C}$ . Pre-conditioning is performed with MSL level 3 based on J-STD-020. Typical values are the highest average  $\pm 3$  sigma across all qualification lots.

### 10.3. Timing specifications

Operating Parameters  $T_A = -40$  to  $150^\circ\text{C}$ ,  $V_{DD}=5$  V or 3.3 V factory trimmed unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Step Response Time	$T_{RESP}$	Delay between the input signal reaching 90% and the output reaching 90% (see Figure 8)			2	$\mu\text{s}$
Bandwidth	BW	-3dB, $T_A = 25^\circ\text{C}$ , SF=1 (default)		400		kHz
		SF=2		200		
		SF=3		100		
Power on Delay	$T_{POD}$				1	ms

Table 12: Timing specifications of the high-speed analog output

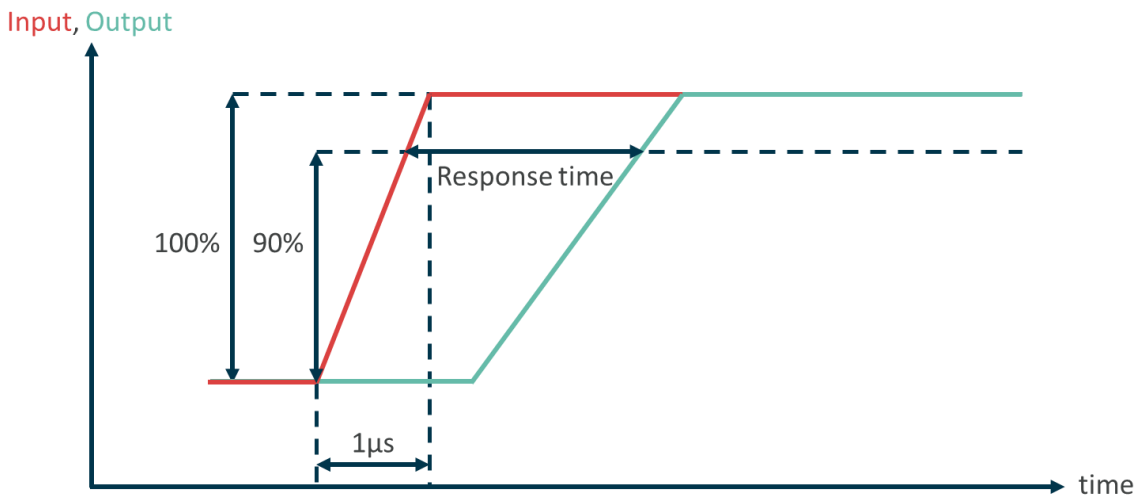


Figure 8: Response Time definition

## 11. Overcurrent Detection Specification<sup>10</sup>

### 11.1. General

The MLX91219 provides two OCD features (called internal and external) that allow the detection of overcurrent events. The internal OCD (OCD<sub>INT</sub>) is available in both packages SIP4-VA and SOIC8, while the external OCD (OCD<sub>EXT</sub>) is only available in SOIC8 package. When an overcurrent event occurs, the OCD pins are pulled to ground. During normal operation the OCD voltage remains at V<sub>DD</sub>. If not used, OCD pins can be connected to GND.

The two OCD functions are able to react to an overcurrent event within few  $\mu$ s of response time. To avoid false alarm, the overcurrent has to be maintained for at least 1 $\mu$ s for the detection to occur. After detection by the sensor the output flag is maintained for 10 $\mu$ s of dwell time. This allows the overcurrent to be easily detected at microcontroller level.

The following table offers a comparison between OCD<sub>INT</sub> and OCD<sub>EXT</sub>:

Description	OCD <sub>INT</sub>	OCD <sub>EXT</sub>
Typical Application	Short-circuit detection	Out-of-range detection
Overcurrent effect	OCD <sub>INT</sub> pin to GND	OCD <sub>EXT</sub> pin to GND
Detection mode	Bidirectional	Unidirectional / bidirectional
Threshold trimming	EEPROM	Voltage divider on VOC <sub>EXT</sub>
Availability in package	SIP4-VA, SOIC8	SOIC8

Table 13: Comparison between OCD<sub>INT</sub> and OCD<sub>EXT</sub>

<sup>10</sup> More information can be found in Application Note ANCurrent\_sensors\_gen2\_OverCurrentDetection on [www.melexis.com](http://www.melexis.com).

## 11.2. Electrical Specifications

Operating Parameters  $T_A = -40$  to  $150^\circ\text{C}$ ,  $V_{DD}=5$  V or 3.3 V factory trimmed unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
OCD_INT Internal ON Resistance	$R_{ON\_OCD\_INT}$	$I_{SINK} = 1$ mA	60	90	150	$\Omega$
OCD_EXT Internal ON Resistance	$R_{ON\_OCD\_EXT}$	$I_{SINK} = 1$ mA	160	190	280	$\Omega$
VOC_EXT Voltage Range $V_{DD}= 5$ V, 5xx versions	$VOC_{EXT\_5V}$	RS = 0 , Bidirectional RS = 3, Unidirectional	0.5 0.9		2.0 4.5	V
VOC_EXT Voltage Range $V_{DD}= 3.3$ V, 3xx versions	$VOC_{EXT3V3}$	RS = 1, Bidirectional RS = 3, Unidirectional	0.5 0.74		1.525 2.9	V
OCD_INT accuracy	OCD_INT	Ratiometric output <sup>11</sup>		$\pm 10$		%Thr <sup>12</sup>
OCD_EXT accuracy	OCD_EXT			$\pm 1.5$		%FS

Table 14: Electrical Specifications OCD

## 11.3. Timing Specifications

Operating Parameters  $T_A = -40$  to  $150^\circ\text{C}$ ,  $V_{DD}=5$  V or 3.3 V factory trimmed unless otherwise specified.

Parameter	Test Conditions	Min	Typ	Max	Units
OCD_INT response time	programmable		1.4 2.1		$\mu\text{s}$
OCD_EXT response time			10		$\mu\text{s}$
OCD_INT required Input holding time			0.5		$\mu\text{s}$
OCD_EXT required Input holding time			10		$\mu\text{s}$
OCD_INT output dwell time		7		14	$\mu\text{s}$
OCD_EXT output dwell time			10		$\mu\text{s}$

Table 15: OCD\_INT and OCD\_EXT timing specifications

<sup>11</sup> OCD\_INT threshold will not scale with VDD variation (in ratiometric output mode) therefore at lower supply voltage results in a higher OCD\_INT threshold and vice versa. VDD variation should be accounted for when defining the OCD threshold.

<sup>12</sup> The error of OCD\_INT is expressed as percentage of the threshold value. Example: if the nominal threshold is 282mT, the typical threshold of OCD\_INT will be in the range between 253.8mT and 310.2



## 11.4. Internal Overcurrent Detection Principle

The internal OCD takes the threshold voltage values predefined in the EEPROM and does not require any extra components. The  $OCD_{INT}$  implementation allows detecting overcurrent outside of the output measurement range of the sensor and is therefore suitable for large current peaks as occurring during short-circuit. If the theoretical sensor output overcomes the  $OCD_{INT}$  voltage threshold, the overcurrent event is flagged on  $OCD_{INT}$  pin. The default OCD threshold voltages are defined as follows, but other values can be set on request.

Sensor reference	Typical Sensitivity [mV/mT]	$OCD_{INT}$ Threshold Current [%FS]
MLX91219LVA-AAA-500	7	136
MLX91219LVA-AAA-501	10	136
MLX91219LDC-ARA-501	10	142
MLX91219LVA-AAA-502	15	136
MLX91219LVA-AAA-503	25	136
MLX91219LVA-AAT-505	10	90

Table 16:  $OCD_{INT}$  thresholds

	Sensor configuration	Min [% FS]	Max [% FS]
$OCD_{INT}$ Threshold	$V_{DD} = 5V / V_{REF} = 2.5V$	24	221

Table 17:  $OCD_{INT}$  factory programmable range

## 11.5. External Overcurrent Detection Principle

The external OCD uses the voltage applied on  $VOC_{EXT}$  pin as threshold voltage. This translates into an overcurrent threshold depending on the sensitivity of the sensor. A voltage divider on  $VOC_{EXT}$  allows defining the threshold voltage in a custom way. Depending on the voltage divider configuration, the  $OCD_{EXT}$  can be used either in bidirectional or unidirectional mode. The External OCD threshold is defined within the measurement range of the sensor output. This feature is then suitable for out-of-range detection where the OCD threshold remains close to the nominal current. It offers a better accuracy than  $OCD_{INT}$  but the response is slower. The below table presents the unidirectional and bidirectional external OCD configurations. Please refer to section 13 for more details about the application diagram and the recommended resistances.

Bidirectional configuration	Unidirectional configuration
$VOC_{EXT} = V_{REF} * \frac{R_4}{R_3 + R_4}$ $VLocd = VOC_{EXT}$ $VHocd = 2 * V_{REF} - VLocd$	$VOC_{EXT} = V_{REF} + (V_{DD} - V_{REF}) * \frac{R_{4bis}}{R_3 + R_{4bis}}$ $VHocd = VOC_{EXT}$

Table 18: External OCD, bidirectional and unidirectional configurations

## 12. Recommended Application Diagram

### 12.1. SIP-4 VA Package

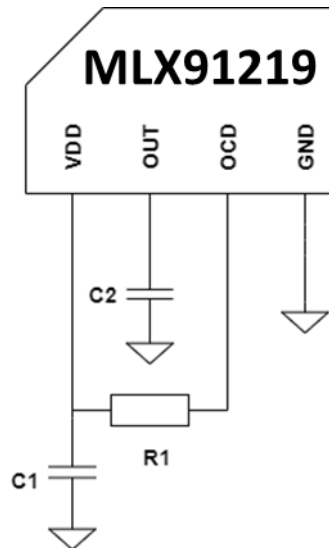


Figure 9: Application Diagram for SIP-4 VA package

Part	Description	Value	Unit
C1	Supply capacitor, EMI, ESD	47	nF
C2	Decoupling, EMI, ESD	4.7	nF
R1	Internal OCD resistor	10	kΩ

Table 19: Resistor and capacitor values for SIP-4 VA package

## 12.2. SOIC8 package

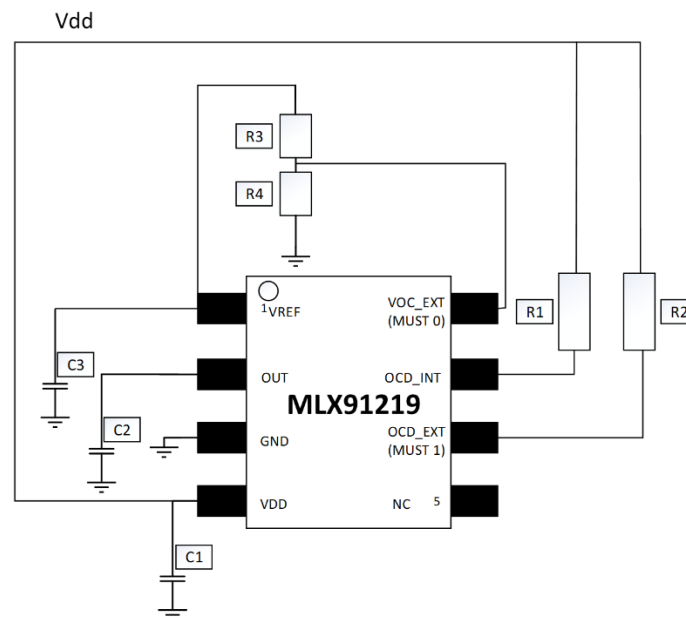


Figure 10: Application Diagram for SOIC8 package

Part	Description	Value	Unit
C1	Supply capacitor, EMI, ESD	47	nF
C2	Decoupling, EMI, ESD	4.7	nF
C3	Decoupling, EMI, ESD	47	nF
R1	Internal OCD resistor	10	kΩ
R2	External OCD resistor	10	kΩ
R3/R4/R4bis	Uni-/Bidirectional OCD customized ratio	-	kΩ

Table 20: Resistor and capacitor values for SOIC8 package

## 13. Standard Information

Our products are classified and qualified regarding soldering technology, solderability and moisture sensitivity level according to following test methods:

### Reflow Soldering SMD's (Surface Mount Devices)

- IPC/JEDEC J-STD-020  
Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices (classification reflow profiles according to table 5-2)
- EIA/JEDEC JESD22-A113  
Preconditioning of Nonhermetic Surface Mount Devices Prior to Reliability Testing (reflow profiles according to table 2)

### Wave Soldering SMD's (Surface Mount Devices) and THD's (Through Hole Devices)

- EN60749-20  
Resistance of plastic- encapsulated SMD's to combined effect of moisture and soldering heat
- EIA/JEDEC JESD22-B106 and EN60749-15  
Resistance to soldering temperature for through-hole mounted devices

### Iron Soldering THD's (Through Hole Devices)

- EN60749-15  
Resistance to soldering temperature for through-hole mounted devices  
Soldering by iron or other methods that require a peak temperature equal or above 350degC are not allowed.

### Solderability SMD's (Surface Mount Devices) and THD's (Through Hole Devices)

- EIA/JEDEC JESD22-B102 and EN60749-21  
Solderability

For all soldering technologies deviating from above mentioned standard conditions (regarding peak temperature, temperature gradient, temperature profile etc.) additional classification and qualification tests have to be agreed upon with Melexis. The application of Wave Soldering for SMD's is allowed only after consulting Melexis regarding assurance of adhesive strength between device and board.

Melexis recommends reviewing on our web site the General Guidelines soldering recommendation (<https://www.melexis.com/en/quality-environment/soldering>).

Melexis is contributing to global environmental conservation by promoting **lead free** solutions. For more information on qualifications of **RoHS** compliant products (RoHS = European directive on the Restriction Of the use of certain Hazardous Substances) please visit the quality page on our website (<https://www.melexis.com/en/quality-environment>).

For package technology embedding trim and form post-delivery capability, Melexis recommends to consult the dedicated trim and form recommendation application note: [Lead trimming and forming recommendations](#).

## 14. ESD Precautions

Electronic semiconductor products are sensitive to Electro Static Discharge (ESD). Always observe Electro Static Discharge control procedures whenever handling semiconductor products.

## 15. Packaging information: SIP4-VA

### 15.1. Sensor active measurement direction and magnetic center

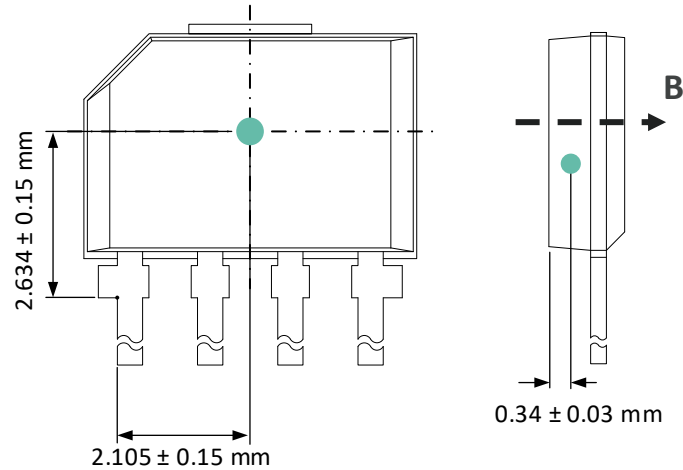


Figure 11: VA/SIL-4L Magnetic center and sensor's active measurement direction B

### 15.2. Package marking & Hall plate position

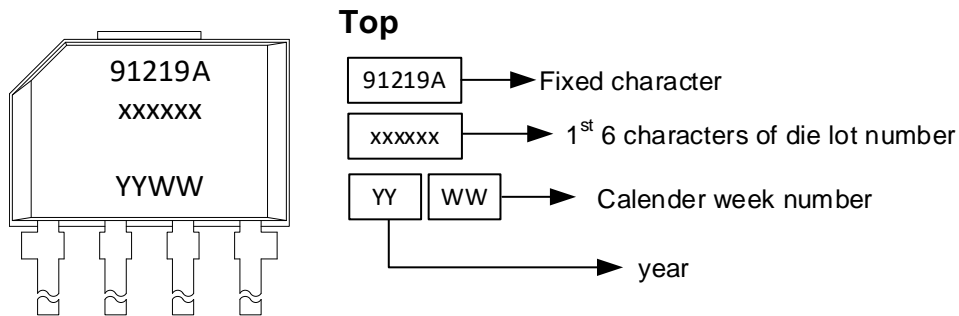
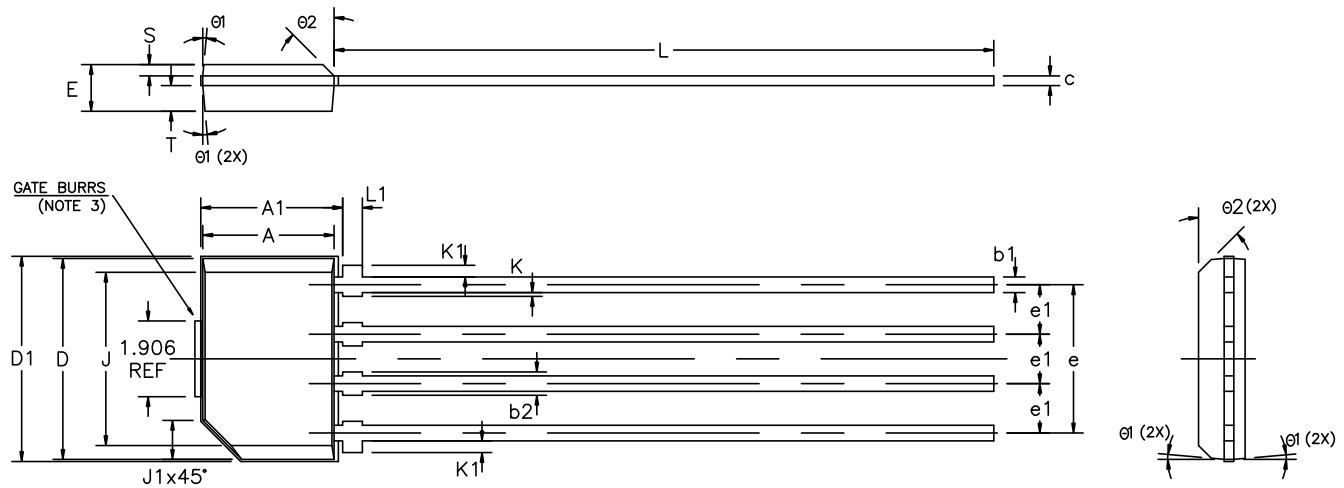


Figure 12. VA/SIP 4L (single in-line package) / 18mm lead length - Package Information

### 15.3. VA Straight leg (MLX91219LVA-ARA-xxx-xx)



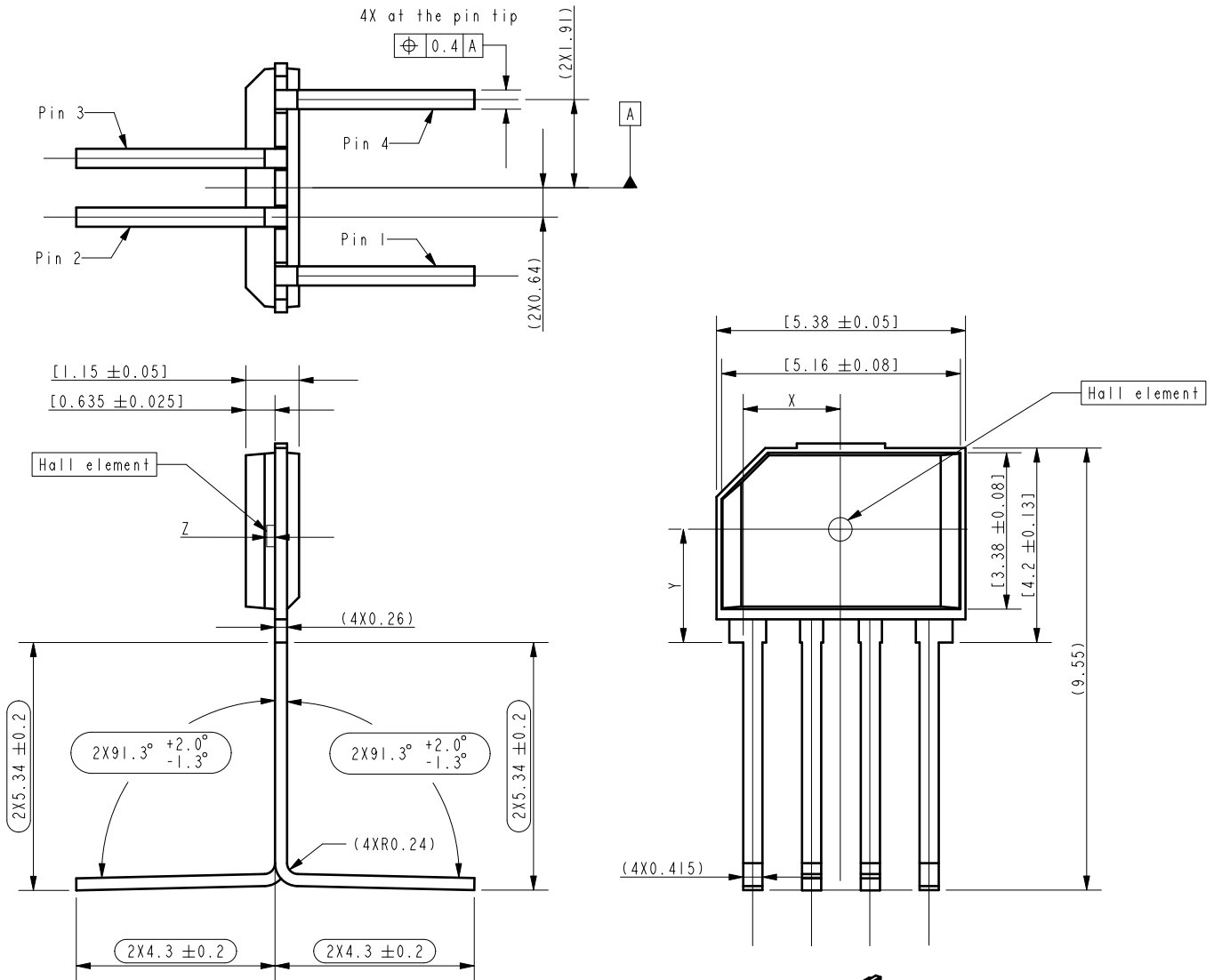
SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	3.30	3.38	3.46
A1	3.63	3.71	3.79
D	5.08	5.16	5.24
D1	5.33	5.38	5.43
E	1.10	---	1.20
J	4.10	4.30	4.50
J1	1.00 REF		
K	0.00	---	0.15
K1	0.25	0.30	0.35
L	17.5	18.0	18.5
L1	0.48	0.53	0.58
S	0.24	---	0.29
T	0.61	---	0.66
b1	0.35	---	0.48
b2	0.40	---	0.60
c	0.18	---	0.34
e	3.76	---	3.86
e1	1.22	1.27	1.32
Ø1	5° REF		
Ø2	45° REF		

**Note:**

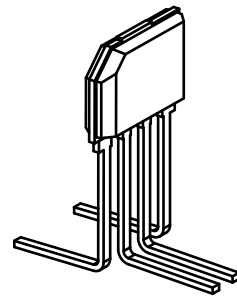
1. DIMENSIONS "A" AND "D" DO NOT INCLUDE MOLD FLASH, PROTRUSIONS AND GATE BURRS.
2. DIMENSIONS "A1" DOES NOT INCLUDE GATE BURRS BUT INCLUDES MOLD FLASH AT BOTH ENDS.
3. MOLD GATE BURRS SHALL NOT EXCEED 0.15 mm MEASURED FROM EDGE OF MOLD FLASH (FLANGE).
4. DIMENSION "D1" INCLUDES MOLD FLASH AT BOTH ENDS.
5. LEAD PLATING; MATTE TIN PLATING THICKNESS 7.62 – 15.42  $\mu$ m.
6. THE LEADS MAY BE SLIGHTLY DEFORMED DURING TRANSPORTATION IF PACKED IN BULK (BAG), AFFECTING e1 DIMENSION. IT IS RECOMMENDED TO ORDER RADIAL TAPE (REEL OR AMMOPACK) IF SUCH DEFORMATION IS CRITICAL FOR THE LEAD FORMING PROCESS, EVEN IF MANUAL LOADING INTO THE TOOL IS FORESEEN.

Figure 13: VA Straight leg

15.4. Trim and form-variant TF-VA-2L-1.27-5.34-91.3-4.3



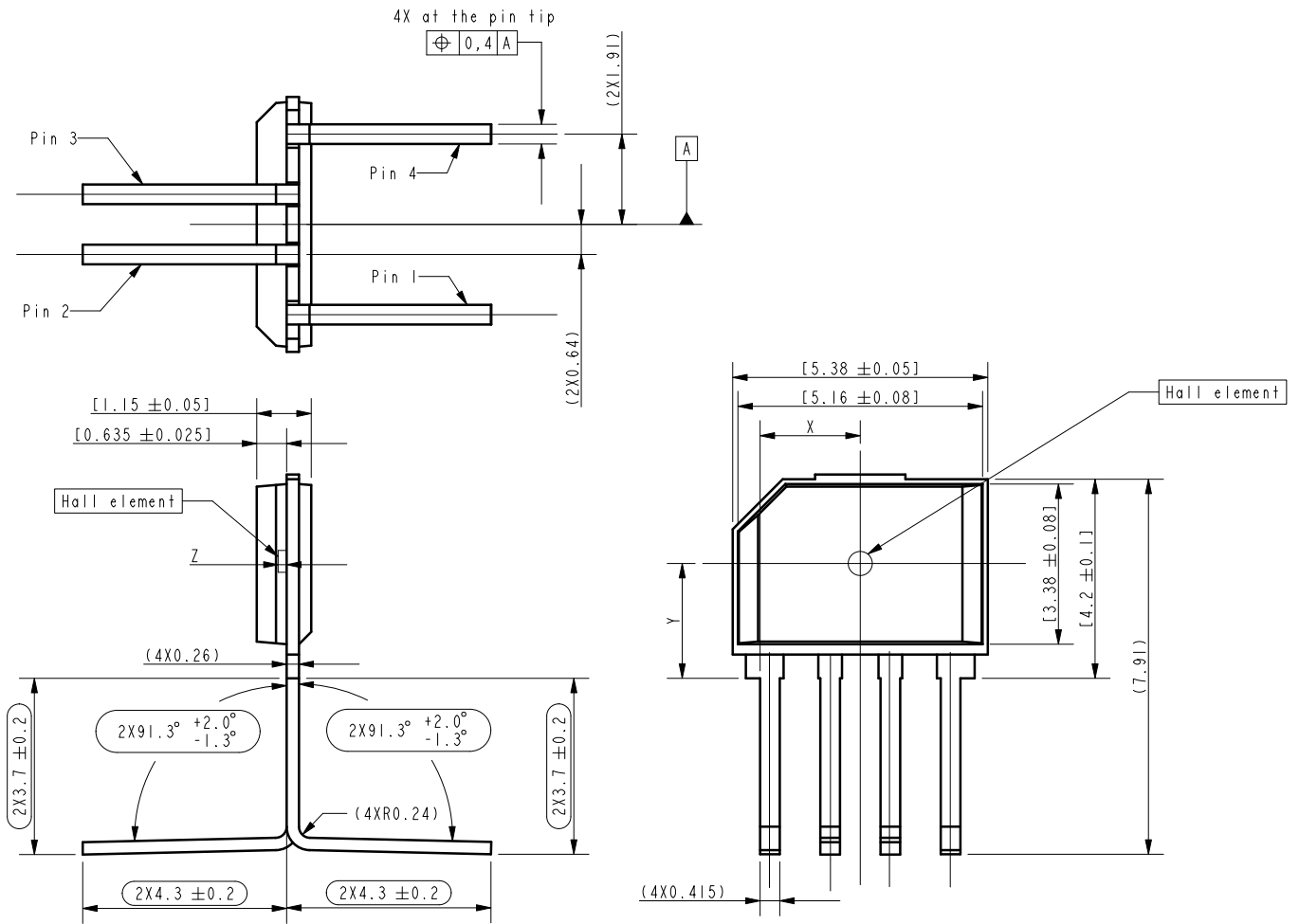
- Notes:
1. All controlling dimensions are in millimeters
  2. Lead frame material: Alloy C151
  3. Lead frame plating material: Spot silver
  4. Gate burrs shall not exceed 0.15mm measured from edge of mold flash (flange)
  5. Dimensions in ellipse are representing the inspection values.
  6. Dimensions "X", "Y" and "Z" may vary depending on specific product.
  - Exact dimensions could be found in Melexis datasheet
  7. Dimensions in "( )" are for information.
  8. Dimensions in "[ ]" are values from previous manufacturing step



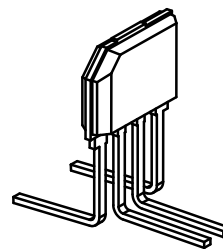
Isometric view  
 Scale 5:1

Figure 14: Trim and form type: 90° 2x2x91.3 (h=5.34), bending-STD2 (AAR-xxx)

15.5. Trim and form-variant TF-VA-2L-1.27-3.7-91.3-4.3



- Notes:
1. All controlling dimensions are in millimeters
  2. Lead frame material: Alloy C151
  3. Lead frame plating material: Spot silver
  4. Gate burrs shall not exceed 0.15mm measured from edge of mold flash (flange)
  5. Dimensions in ellipse are representing the inspection values.
  6. Dimensions "X", "Y" and "Z" may vary depending on specific product.
  7. Dimensions in "()" are for information.
  8. Dimensions in "[]" are values from previous manufacturing step
- Exact dimensions could be found in Melexis datasheet

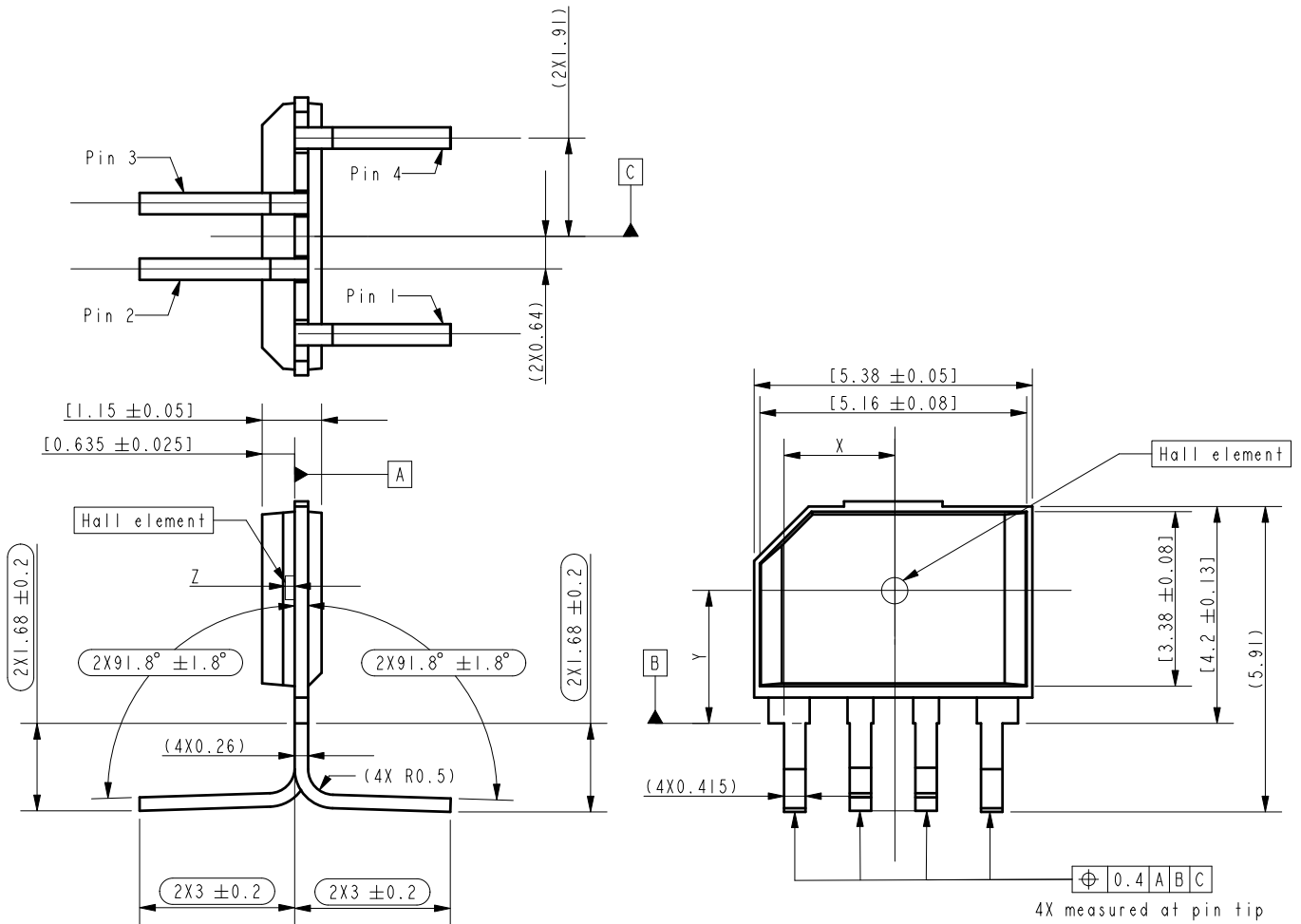


Isometric view  
 Scale 5:1

Figure 15: Trim and form type: 90° 2x2x91.3 (h=3.7), bending-STD3 (AAS-xxx)

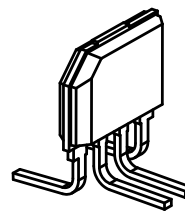


15.6. Trim and form-variant TF-VA-2L-1.27-1.68-91.8-3



Notes:

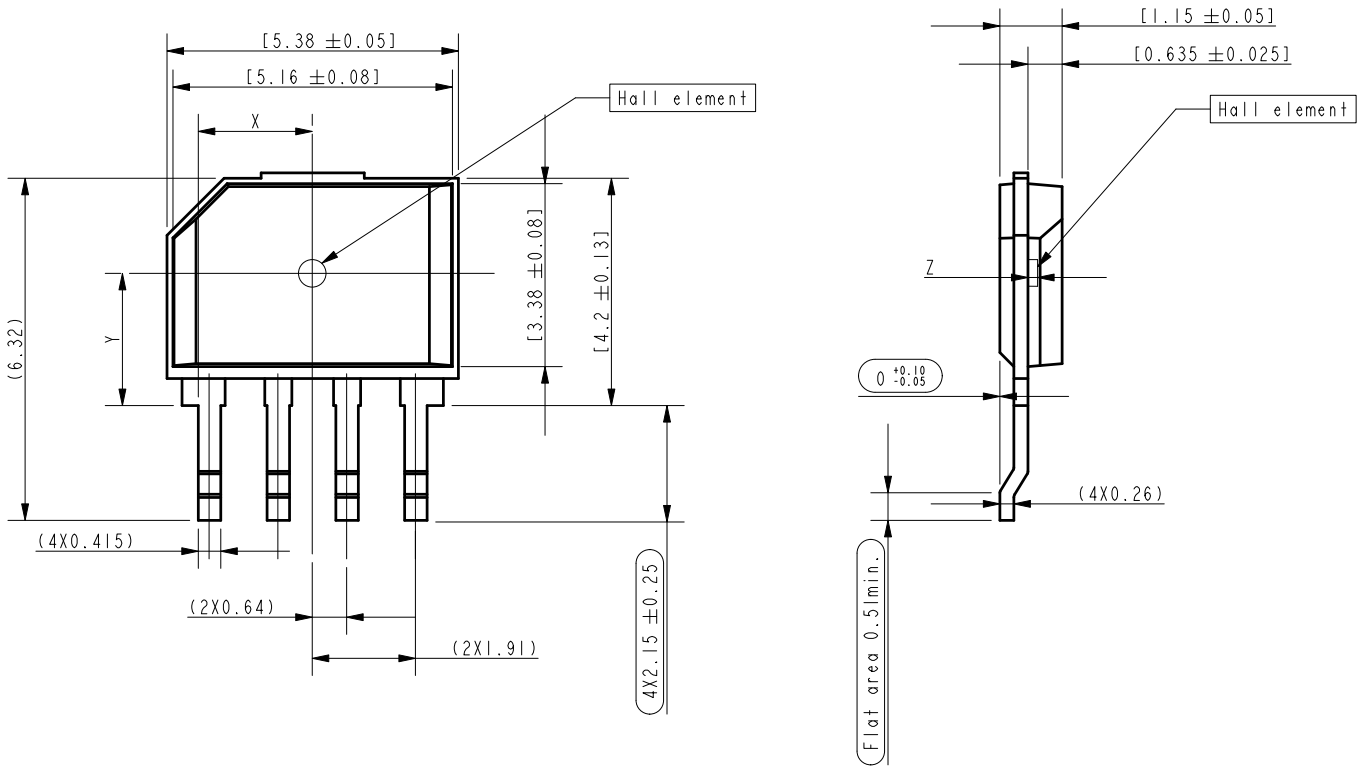
1. All controlling dimensions are in millimeters
2. Lead frame material: Alloy C151
3. Lead frame plating material: Spot silver
4. Gate burrs shall not exceed 0.15mm measured from edge of mold flash (flange)
5. Dimensions in ellipse are representing the inspection values.
6. Dimensions "X", "Y" and "Z" may vary depending on specific product. Exact dimensions could be found in Melexis datasheet
7. Dimensions in "( )" are for information.
8. Dimensions in "[ ]" are values from previous manufacturing step



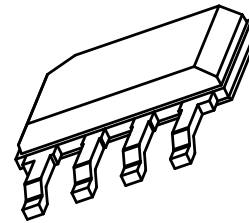
Isometric view  
 Scale 5:1

Figure 16: Trim and form type: 90° 2x2x91.8 (h=1.68), bending-STD4 (AAT-xxx)

15.7. Trim and form-variant TF-VA-ZB-1.27-2.15



- Notes:
1. All controlling dimensions are in millimeters
  2. Lead frame material: Alloy Cl5l
  3. Lead frame plating material: Spot silver
  4. Gate burrs shall not exceed 0.15mm measured from edge of mold flash (flange)
  5. Dimensions in ellipse are representing the inspection values.
  6. Dimensions "X", "Y" and "Z" may vary depending on specific product. Exact dimensions could be found in Melexis datasheet
  7. Dimensions in "( )" are for information.
  8. Dimensions in "[ ]" are values from previous manufacturing step



Isometric view  
 Scale 5:1

Figure 17: Trim and form SMD style TFT4K1 (AAZ-xxx)

## 16. Packaging information: SOIC8

### 16.1. Sensor active measurement direction and magnetic center

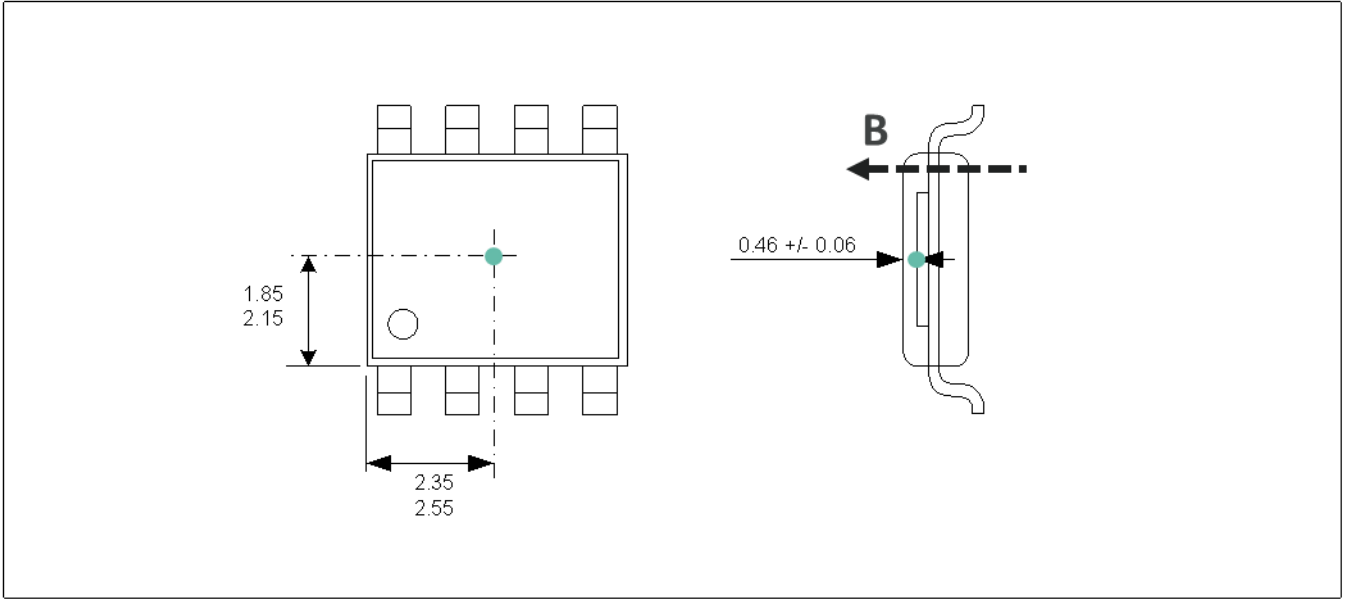


Figure 18: VA/SIL-4L Magnetic center and sensor's active measurement direction B

### 16.2. Package marking

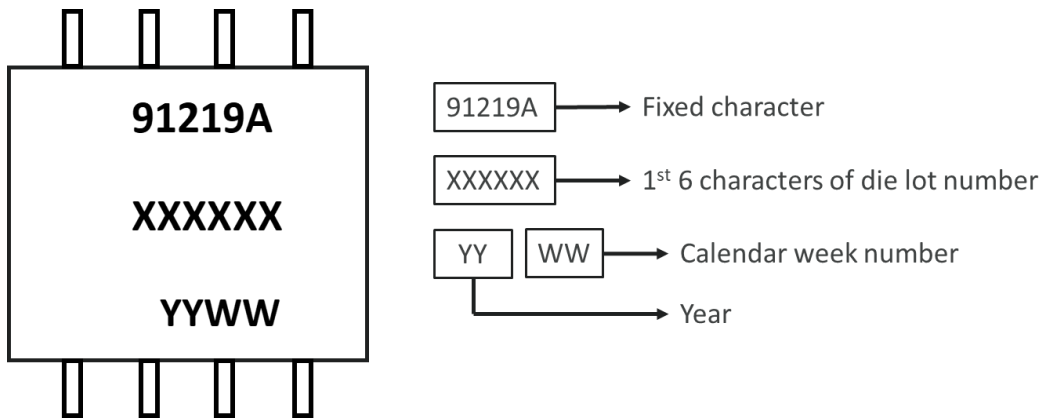
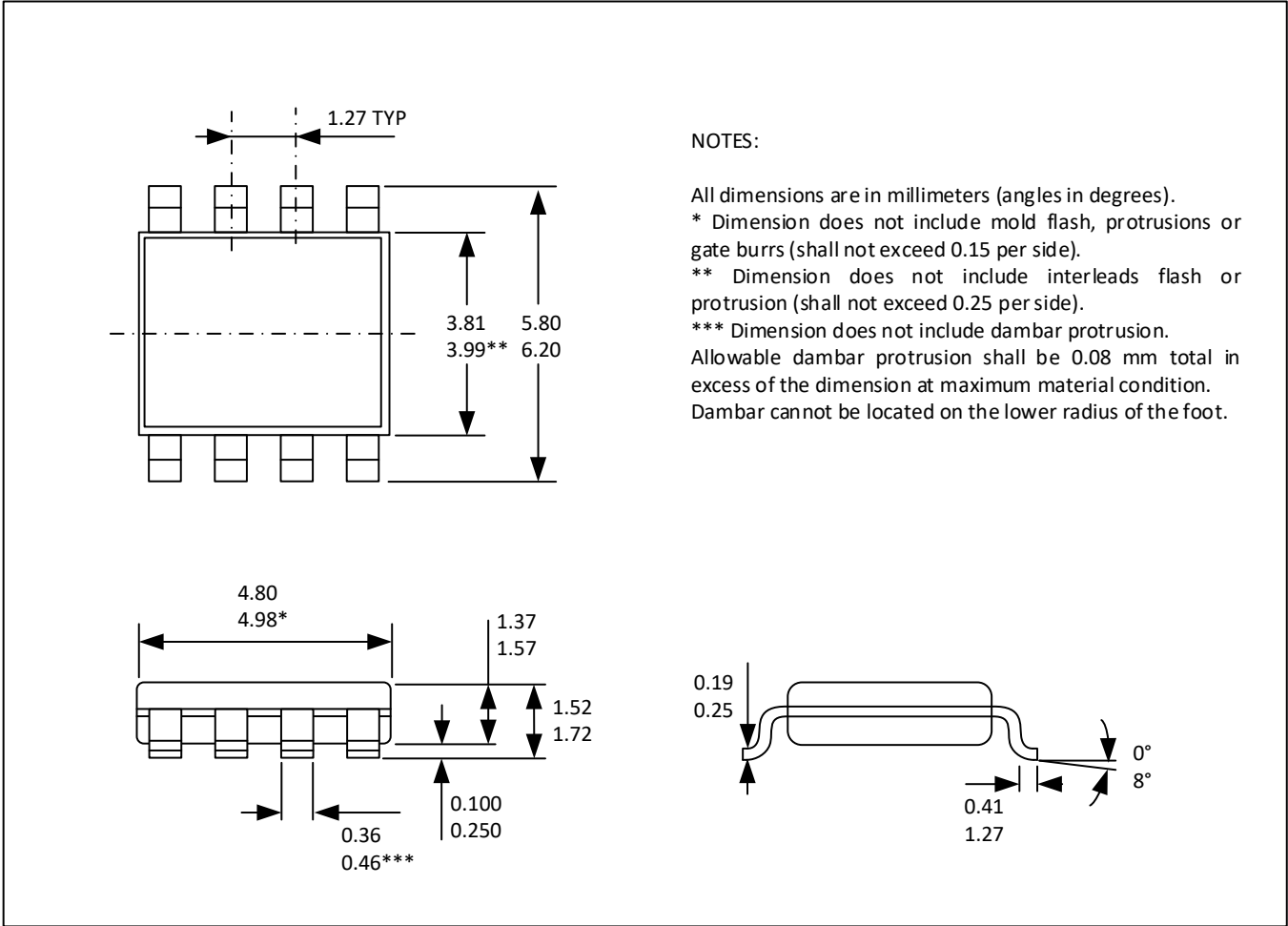


Figure 19. SOIC8 package marking

16.3. Package dimensions



NOTES:

All dimensions are in millimeters (angles in degrees).

\* Dimension does not include mold flash, protrusions or gate burrs (shall not exceed 0.15 per side).

\*\* Dimension does not include interleads flash or protrusion (shall not exceed 0.25 per side).

\*\*\* Dimension does not include dambar protrusion.

Allowable dambar protrusion shall be 0.08 mm total in excess of the dimension at maximum material condition.

Dambar cannot be located on the lower radius of the foot.

Figure 20: SOIC8 package

## 17. Contact

For additional information, please contact our Direct Sales team and get help for your specific needs:

Europe, Africa	Email : sales_europe@melexis.com
Americas	Email : sales_usa@melexis.com
Asia	Email : sales_asia@melexis.com

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